

Appl. No. 10/627,609
Amendment dated: April 26, 2005
Reply to OA of: January 31, 2005

Amendments to the Specification:

Please replace paragraph [0022] on page 5 which bridges page 6 with the following amended paragraph.

[0022] Via 440 can be formed by a mechanical method or a chemical method, and the via 440 can be a through hole, a buried via or a blind via. Metal layers 450a and 450b can be formed on the inner wall 442 of the via 440 by the method of electro-less plating or direct plating. Via lands 460a and 460b are disposed on the board 400 and at the periphery of the via 440, and the material of the via lands 460a and 460b are with good electrical conductivity. Generally speaking, the material of the via lands 460a and 460b is substantially the same as the conductive traces 430a and 430b, for example copper metal. The via 440 is filled with an insulator 480 which separates the via 440 into a plurality of separated vias (not shown), and the metal layers 450a and 450b are electrically isolated from each other by the insulator 480. In addition, the via lands 460a and 460b are also electrically isolated from each other. The insulator 480 can be made of insulating materials, for example epoxy resin and ink. Besides, the metal layers ~~[[430a]]~~ 450a and ~~[[430b]]~~ 450b are electrically connected with the conductive traces 430a and 430b through the via lands 460a and 460b.